

Application Data Sheet

Application Information

Application number::	09802664
Filing Date::	03/09/01
Application Type::	Regular
Subject Matter::	Utility
Title::	Flip Chip Interconnection Structure
Attorney Docket Number::	CPAC 1003-1
Request for Early Publication?::	No
Request for Non-Publication?::	No
Total Drawing Sheets::	3
Small Entity?::	No

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	US
Status::	Full Capacity
Given Name::	Rajendra
Middle Name::	D.
Family Name::	Pendse
City of Residence::	Fremont
State or Province of Residence::	CA
Country of Residence::	US
Street of mailing address::	5245 Diamond Common
City of mailing address::	Fremont
State or Province of mailing address::	CA
Country of mailing address::	US
Postal or Zip Code of mailing address::	94555

Correspondence Information

Correspondence Customer Number:: 22470

Representative Information

Representative Customer Number::	22470	
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Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	An application claiming the benefit under 35 USC 119(e)	60188570	03/10/2000

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::

Assignee Information

Assignee name:: ChipPAC, Inc
Street of mailing address:: 47400 Kato Road
City of mailing address:: Fremont
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94538